

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	2038231	@ad>"20030730" @rad>"20030730" @pt1d>"20030730"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 15:05
L5	138	(polyimide near5 solder adj resist) not L3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 14:51
L6	34	(US-20020027010-\$ or US-20020094606-\$ or US-20020039808-\$).did. or (US-4530152-\$ or US-5218759-\$ or US-5900676-\$ or US-5976912-\$ or US-6001671-\$ or US-6130473-\$ or US-6198165-\$ or US-6247229-\$ or US-6255740-\$ or US-6294830-\$ or US-6342730-\$ or US-6586677-\$ or US-6635957-\$ or US-6700188-\$ or US-6770959-\$ or US-6800508-\$ or US-6821821-\$ or US-6833609-\$ or US-6841414-\$ or US-6861295-\$ or US-6872661-\$ or US-6888168-\$ or US-6888228-\$ or US-6933604-\$ or US-6967125-\$ or US-6975022-\$).did. or (US-6365432-\$ or US-6849950-\$ or US-5981311-\$ or US-6093499-\$).did. or (JP-10084010-\$).did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/30 14:39
L8	8704	solder adj resist not 3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 14:51
L9	538	die adj bonding adj material not 3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 14:51
L10	0	8 adj 9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 14:51
L12	4	8 with 9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 14:53
L13	27728	(die chip) adj bond\$5 not 3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 17:17
L14	1	8 adj 13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 14:53
L15	48	8 with 13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 14:53
L16	1	2003-493176.NRAN.	DERWENT	OR	ON	2006/01/30 15:03
L17	4	"2003035744"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 15:05
L18	90914	(die chip) with (bond\$5 adesive) not 3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 17:18
L19	212	8 with 18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 17:18
L20	164	19 not 15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 17:18
L21	13	(back adj side backside) with (chip die) with 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 17:35
L22	78	(adhesive) with (chip die) with 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 18:56

L23	39	(US-20020027010-\$ or US-20020094606-\$ or US-20020039808-\$ or US-20020033524-\$ or US-20030176585-\$ or US-20020041025-\$).did. or (US-4530152-\$ or US-5218759-\$ or US-5900676-\$ or US-5976912-\$ or US-6001671-\$ or US-6130473-\$ or US-6198165-\$ or US-6247229-\$ or US-6255740-\$ or US-6294830-\$ or US-6342730-\$ or US-6586677-\$ or US-6635957-\$ or US-6700188-\$ or US-6770959-\$ or US-6800508-\$ or US-6821821-\$ or US-6833609-\$ or US-6841414-\$ or US-6861295-\$ or US-6872661-\$ or US-6888168-\$ or US-6888228-\$ or US-6933604-\$ or US-6967125-\$ or US-6975022-\$).did. or (US-6365432-\$ or US-6849950-\$ or US-5981311-\$ or US-6093499-\$ or US-6265783-\$).did. or (JP-10084010-\$ or JP-2001354938-\$).did.	US-PGPUB; USPAT; DERWENT	OR	ON	2006/01/30 18:57
L24	26	23 and tape	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 18:58
L25	9	23 and (tape with film)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 19:17
L26	11	23 and (ultraviolet ultra adj violet excimer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 19:17
S1	2	("20050023682").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/30 17:28
S2	2015570	@ad>"20030730" @riad>"20030730" @pt1d>"20030730"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/24 18:47
S5	989	438/759,940,977,for.485.ccls. not S2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 20:29
S6	87	encaps\$ and S5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/24 18:48
S7	33	("20020125559" "5286656" "5656550" "5714800" "6001671" "6130473" "6150709" "6177722" "6190938" "6198165" "6229200" "6255740" "6281047" "6284563" "6294830" "6342730" "6350668" "6372539" "6399415" "6405359" "6448633" "6451627" "6452255" "6455348" "6498099" "6545347" "6585905" "6635957" "6686652" "6689640" "6700188" "6777788" "6812552").PN. OR ("6967125").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/24 18:52
S8	33	S7 not S2	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/24 18:55
S9	2	("5,900,676").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/24 18:55
S10	968	temporary adj substrate not S2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/24 19:26
S11	117	encaps\$ and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/24 19:26
S12	117	S11 not (S6 S8)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/24 19:26
S13	266	("3657805" "3781596" "3982979" "4530152" "4566184" "4672418" "4890383" "4899207" "5066831" "5122860" "5148265" "5148266" "5157475" "5157480" "5177591" "5200362" "5273938" "5293072" "5294827" "5302849" "5309429" "5355283" "5367766" "5373190" "5418186" "5436203" "5444301" "5457340" "5468999" "5474958" "5487999" "5521429" "5554887" "5557150" "5559364" "5581444" "5608265" "5620928" "5659200" "5710695" "5729437" "5777382" "5835988" "5844315" "5849608" "5894108" "5900676" "5929522" "5937512" "5976912" "5977613" "6001671" "6057601" "6072239" "6143981" "6166430" "6187614" "6191494" "6194786" "6198171" "6201292" "6208023" "6229200" "6247229" "6294830" "6333252" "6342730" "6459163").PN. OR ("20020027010" "5900676" "6001671" "6130473" "6247229" "6294830" "6342730" "6586677" "6635957").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/24 19:34
S17	227	S13 not (S6 S8 S12 S2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/24 19:34
S18	7	("5866948" "5869905" "5976912" "6001671" "6111306" "6191494" "6455926").PN. OR ("6770959").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/24 19:53

S19	7	S18 not S2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/24 19:53
S21	2020555	@ad>"20030730" @riad>"20030730" @pt1d>"20030730"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 12:50
S22	181	fukutoml.in. and hltachl.as. not S21	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 12:50
S23	2	("6849950").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/26 17:14
S24	0	liquid adj epoxy adj solder adj resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 19:20
S25	10	liquid adj epoxy with solder adj resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 19:20
S26	32	(US-20020027010-\$ or US-20020094606-\$ or US-20020039808-\$).did. or (US-4530152-\$ or US-5218759-\$ or US-5900676-\$ or US-5976912-\$ or US-6001671-\$ or US-6130473-\$ or US-6198165-\$ or US-6247229-\$ or US-6255740-\$ or US-6294630-\$ or US-6342730-\$ or US-6586677-\$ or US-6635957-\$ or US-6700188-\$ or US-6770959-\$ or US-6800508-\$ or US-6821821-\$ or US-6833609-\$ or US-6841414-\$ or US-6861295-\$ or US-6872661-\$ or US-6888168-\$ or US-6888228-\$ or US-6933604-\$ or US-6967125-\$ or US-6975022-\$).did. or (US-6365432-\$ or US-6849950-\$).did. or (JP-10084010-\$).did.	US-PGPUB; USPAT; DERWENT	OR	ON	2006/01/26 19:36
S27	11	foil and S26	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 20:23
S28	4	(foil with tape) and S26	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 19:38
S31	2020555	@ad>"20030730" @riad>"20030730" @pt1d>"20030730"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 20:24
S32	16	copper adj foil with copper adj tape not S31	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 20:28
S33	2042	(copper with foil with tape) not S31	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 20:35
S34	989	438/759,940,977,for.485.ccls. not S31	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 20:29
S35	1	S33 and S34	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 20:31
S38	2239208	semiconductor integrated adj circuit ic ("438"/\$ "257"/\$).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 20:34
S40	1031	S38 and S33	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 20:34
S41	0	(cu with foil with tape) and S34	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 20:36
S42	2219	((cu copper) with foil with tape) not S31	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 20:36

S44	467	((cu copper) with foil with tape with carrier) not S31	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 20:38
S45	348	S44 and S38	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 20:36
S46	365	((cu copper) with foil with tape with carrier not with polyimide) not S31	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 20:40
S47	266	S46 and S38	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 20:39
S48	280	((cu copper) with foil with tape with carrier not with (polyimide adhesive Insulat\$)) not S31	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 20:41
S49	207	S48 and S38	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 20:51
S50	6	(temporary removable) with S42	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/26 20:54
S53	2	"59074657"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 13:43